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(54) **CIRCUIT BOARD AND MANUFACTURING METHOD THEREOF, AND TERMINAL DEVICE**

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(57)   **ABSTRACT**

This application discloses a circuit board and a manufacturing method thereof, and a terminal device, and relates to the technical field of terminals, to resolve the problem of low reliability of connection between a radio frequency front-end circuit and a radio frequency back-end circuit in a circuit board of a terminal device in a related technology. The circuit board includes a substrate and a liquid metal body, where the substrate is provided with a radio frequency front-end circuit, a radio frequency back-end circuit, and a pad group, where the pad group includes a first pad electrically connected to the radio frequency front-end circuit and a second pad electrically connected to the radio frequency back-end circuit, and the second pad is spaced apart from the first pad; and the liquid metal body is arranged at a position of the pad group and connects the first pad to the second pad, so as to electrically connect the radio frequency front-end circuit to the radio frequency back-end circuit. This application may be applied to a terminal device such as a mobile phone.